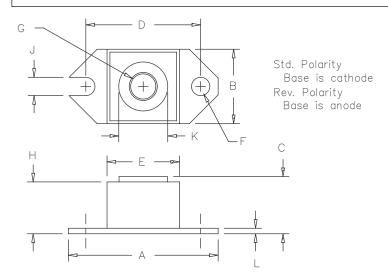
240 Amp Schottky Rectifier HS247180-HS247200



Dim.	Inches		Millimeter		
	Minimum	Maximum	Minimum	Maximum	Notes
A B C D E F	1.52 .725 .605 1.182 .745 .152	1.56 .775 .625 1.192 .755	38.61 18.42 15.37 30.02 18.92 3.86	39.62 19.69 15.88 30.28 19.18 4.06	Sq. Dia.
G H J K L	.525 .156 .495 .120	1/4-20 .580 .160 .505 .130	UNC-2B 13.34 3.96 12.57 3.05	14.73 4.06 12.83 3.30	Dia.

Microsemi Industry Working Peak Repetitive Peak
Catalog Number Part Number Reverse Voltage Reverse Voltage
HS247180* 180V 180V
HS247200* 200V

*Add Suffix R for Reverse Polarity

- Schottky Barrier Rectifier
- Guard Ring Protection
- 240 Amperes 180-200 Volts
- 175°C Junction Temperature
- Reverse Energy Tested
- ROHS Compliant

Electrical Characteristics

Average forward current
Maximum surge current
Maximum repetitive reverse current
Typical peak forward voltage
Max peak forward voltage
Typical peak reverse current
Max peak reverse current
Typical junction capacitance

| F(AV) 240 Amps | FSM 3300 Amps | R(OV) 2 Amps | VFM 0.65 Volts | VFM 0.86 Volts | RM 150mA | RM 8.0mA | C_J 6000pF TC = 118°C, Square wave, $^{R}\Theta JC$ = .24°C/W 8.3ms, half sine, ^{T}J = 175°C f = 1 KHZ, 25°C I FM = 240A: ^{T}J = 175°C* I FM = 240A: ^{T}J = 25°C* I VRRM ^{T}J = 125°C*

VRRM, TJ = 125°C* VRRM, TJ = 25°C VR = 5.0V, TC = 25°C

*Pulse test: Pulse width 300 µsec, Duty cycle 2%

Thermal and Mechanical Characteristics

Storage temp range
Operating junction temp range
Max thermal resistance
Typical thermal resistance (greased)
Terminal Torque
Mounting Base Torque
Weight

TSTG TJ R OJC R OCS

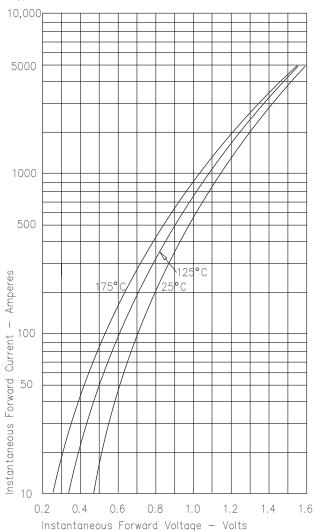
-55°C to 175°C -55°C to 175°C 0.21°C/W Junction to case 0.12°C/W Case to sink 35-40 inch pounds 20-25 inch pounds

1.1 ounces (32 grams) typical



HS247180-HS247200

Figure 1 Typical Forward Characteristics



5.0

10

50

100

Figure 4
Forward Current Derating

0.5 1.0

Reverse Voltage - Volts

1000 -

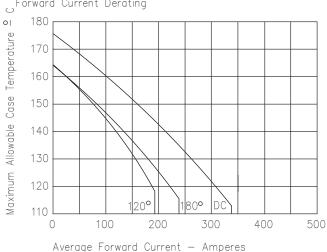


Figure 2 Typical Reverse Characteristics

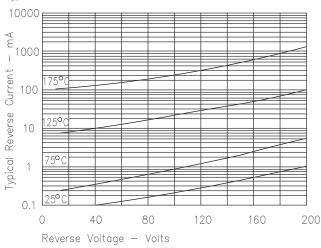
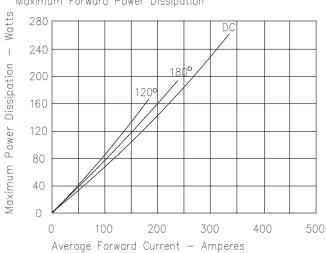


Figure 5 Maximum Forward Power Dissipation





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